





Box Patent Application

Mailed 26 December 2001



Assistant Commissioner for Patents Washington, District of Columbia 20231
Sir: This Application is a Divisional of Ser. No. 09/299,512, filed 26 April 1999; an additional Divisional 09/897,879 is still pending and is <b>not</b> to be abandoned.  A Preliminary Amendment dated 26 December 2001 accompanies this application.  Please file the following enclosed patent application papers:  Applicant # 1, Name: William J. Drasler
Applicant # 2, Name: Joseph M. Thielen
Title: Intravascular Folded Tubular Endoprosthesis
o Specification, Claims, and Abstract: Nr. Of Sheets 130
o Declaration: Date Signed: 26 December 2001
o Drawing(s): Nr of Sheets Enc.: Formal: 62 Informal: 62 Informal: 62 Informal: 63 Informal: 65
o Small Entity Declaration of Inventor(s) o SED of Non-Inventor / Assignee / Licensee
o Assignment enclosed with cover sheet and recordal fee: please record and return.
o Check for \$ 451 for: \$ 370 Filling fee
\$ Independent Claims over 3 \$ Dependent Claims over 20
\$ Additional if Assignment is enclosed for recordal
o Disclosure Document: Information Disclosure Statement plus List of Prior Art
o Request Under MPEP § 707.07(j): The undersigned, a pro se applicant, respectfully requests that if the examiner finds patentable subject matter disclosed in this application, but feels that Applicant's present claims are not entirely suitable, the Examiner draft one or more allowable claims for applicant.  Very respectfully,
Wednes Durch   Joseph m. thicken
Applicant #1 Signature  Applicant #2 Signature
4100 Dynasty Drive, Minnetonka, MN 55345 3027 Cameron Ave., S.E. Buffalo, MN 55313
Address (Send Correspondence Here) Address
Express Mail Label # Date of Deposit 26 December 2001
I hereby certify that this   [EK86915545405] paper or fee is being deposited with the United States
Postal Service Using "Express Mail Post Ofice to Addressee" service under 37 CFR 1.1. on the date indicated above and is
addressed to "Box Patent Application, Assistant Commissioner for Patents, Washington, DC 20231."
Signed: Inventor

Form A:1 Patent Application Transmittal Letter